

BIDIRECTIONAL LOW CAPACITANCE TVS ARRAYS

APPLICATIONS

- ✓ Ethernet 10/100 Base T
- ✔ FireWire
- ✓ SCSI
- ✔ Bluetooth & RF

IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air 15kv, Contact 8kv
- √ 61000-4-4 (EFT): 40A 5/50ns
- ✓ 61000-4-5 (Surge): 24A, 8/20µs Level 2(Line-Gnd) & Level 3(Line-Line)

FEATURES

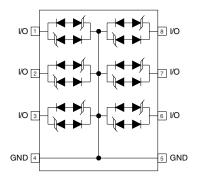
- ✓ 500 Watts Peak Pulse Power Dissipation(t₂ = 8/20µs)
- ✓ Bidirectional Configuration
- ✔ Available in 4 Voltage Types: 3.3V to 15V
- ✔ Protects Up to Six (6) Lines
- ✓ ESD Protection > 40 kilovolts
- **✓ LOW CAPACITANCE-8pF**

MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SO-8
- ✓ Weight 15 milligrams (Approximate)
- ✓ Flammability Rating UL 94V-0
- ✓ 12mm Tape and Reel Per EIA Standard 481-1-A
- ✓ Device Marking Code & Logo
- ✔ Pin 1 Indicated By Dot on Package

SO-8

CIRCUIT DIAGRAM



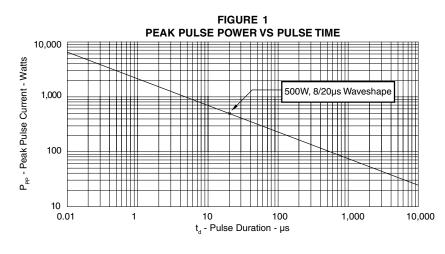
DEVICE CHARACTERISTICS

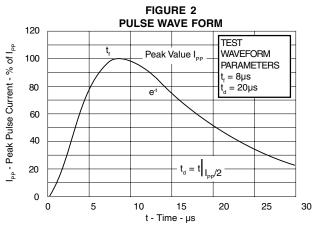
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified						
PARAMETER	SYMBOL	VALUE	UNITS			
Operating Temperature	T_{J}	-55°C to 150°C	℃			
Storage Temperature	T_{STG}	-55°C to 150°C	°C			

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER (See Note 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	TYPICAL CAPACITANCE (See Note 2)
		V _{wM} VOLTS	@ 1mA V _(BR) VOLTS	@ I _P = 1A V _C VOLTS	@8/20μs V _C @ Ι _{ΡΡ}	@ V _{wм} Ι _□ μΑ	0V @ 1 MHz C pF
PLCDA03C-6 PLCDA05C-6 PLCDA08C-6 PLCDA15C-6	PRS PRT PRW PRU	3.3 5.0 8.0 15.0	4.5 6.0 8.5 16.7	7.0 9.8 13.4 22.0	10.9V @ 43.0A 13.5V @ 42.0A 16.9V @ 34.0A 30.0V @ 17.0A	125 20 10 2	8 8 8 8

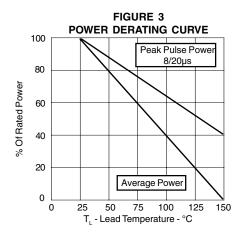
Note 1: Spice model and parameters for this series are available on the ProTek Devices web site: www.protekdevices.com.

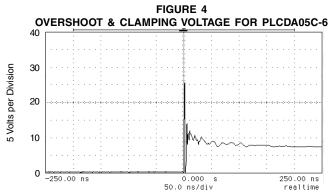
Note 2: Capacitance between I/O pins and ground (pins 4 & 5) is typically 8pF. Capacitance between I/O pins is typically 4 pF.



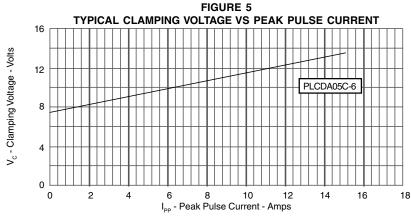


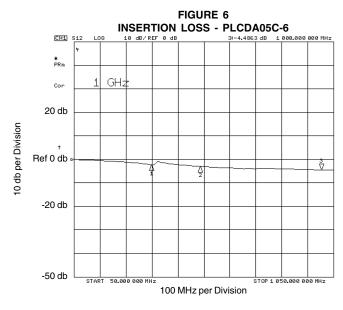
GRAPHS

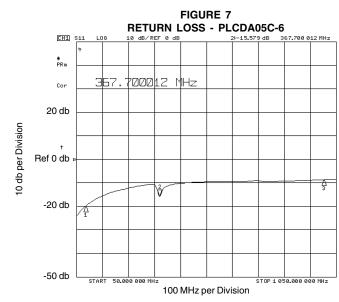




ESD Test Pulse: 25 kilovolt, 1/30ns (waveshape)







APPLICATION NOTE

The PLCDAxxC-6 Series are low capacitance, bidirectional TVS arrays that are designed to protect I/O or high speed data lines from the damaging effects of ESD or EFT. This product series has a surge capability of 500 Watts P_{pp} per line for an 8/20 μ s waveshape and offers ESD protection > 40kv.

BIDIRECTIONAL COMMON MODE CONFIGURATION (Figure 1)

Ideal for use multimode transceiver I/O lines, the PLCDAxxC-6 Series provides up to six (6) lines of protection in a common mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✓ Line 1 is connected to Pin 1.
- ✓ Line 2 is connected to Pin 2.
- ✓ Line 3 is connected to Pin 3.
- ✓ Line 4 is connected to Pin 8.
- ✓ Line 5 is connected to Pin 7.
- ✓ Line 6 is connected to Pin 6.
- ✓ Pins 4 and 5 are connected to Ground.

BIDIRECTIONAL COMMON MODE CONFIGURATION (Figure 2)

The PLCDAxxC-6 Series also provides video line applications six (6) lines of protection in a common mode configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- ✓ Line 1 (Red) is connected to Pin 1.
- ✓ Line 2 (Green) is connected to Pin 2.
- ✓ Line 3 (Blue) is connected to Pin 3.
- ✓ Line 4 (VSYNC) is connected to Pin 6.
- ✓ Line 5 (HSYNC) is connected to Pin 7.
- ✔ Pins 4 and 5 are connected to Ground.

LINE 5 LINE 4 LINE 2 LINE 1

Figure 1: Typical Transceiver Protection Circuit

CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

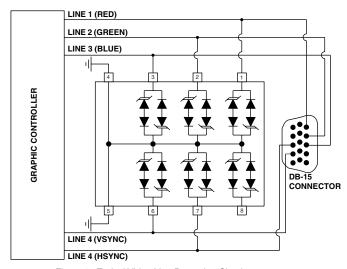
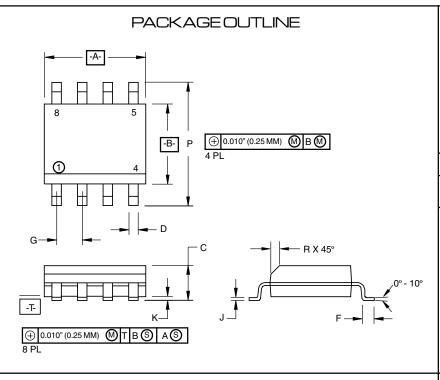


Figure 2: Typical Video Line Protection Circuit

PACKAGE OUTLINE & DIMENSIONS



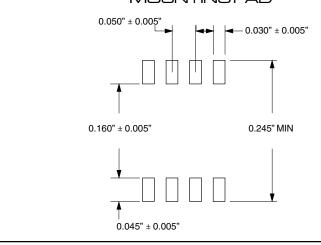
SO-8



PACKAGE DIMENSIONS

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.196	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.250	0.016	0.049	
G	1.27 BSC	1.27 BSC	0.05 BSC	0.05 BSC	
J	0.18	0.25	0.007	0.009	
K	0.10	0.25	0.004	0.008	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

MOUNTINGPAD



NOTES

- 1. T = Seating Plane and Datum Surface.
- 2. Dimensions "A" and "B" are Datum.
- 3. Dimensions "A" and "B" do not include mold protrusion.
- Maximum mold protrusion is 0.015" (0.380 mm) per side.
- 5. Dimensioning and tolerances per ANSI Y14.5M, 1982.
- 6. Dimensions are exclusive of mold flash and metal burrs

06009 Rev 1 -11/01

TAPE & REEL PACKAGING:

Surface mount product is taped and reeled in accordance with EIA-481, reel quantites and sizes are as follows:

7 Inch Reel - 1,000 pieces per reel; 13 Inch Reel - 2,500 pieces per reel

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